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Product Status	Active
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Peripherals	LVD, POR, PWM, WDT
Number of I/O	40
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Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	4K x 8
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Operating Temperature	-40°C ~ 125°C (TA)
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Address	Module	Size (Bytes)
0x03C8-0x03CF	DAC1 (Digital to Analog Converter) ⁸	8
0x03D0-0x03FF	Reserved	48

¹ The SCI1 is not available on the S12GN8, S12GN16, S12GN32, and S12GN32 devices

NOTE

Reserved register space shown in Table 1-3 is not allocated to any module. This register space is reserved for future use. Writing to these locations has no effect. Read access to these locations returns zero.

Figure 1-2 shows S12G CPU and BDM local address translation to the global memory map as a graphical representation. In conjunction Table 1-4 shows the address ranges and mapping to 256K global memory space for P-Flash, EEPROM and RAM. The whole 256K global memory space is visible through the P-Flash window located in the 64k local memory map located at 0x8000 - 0xBFFF using the PPAGE register.

Table 1-4. MC9S12G-Family Memory Parameters

Feature	S12GN16	S12GN32	S12G48 S12GN48	S12G64	S12G96	S12G128	S12G192 S12GA192	S12G240 S12GA240
P-Flash size	16KB	32KB	48KB	64KB	96KB	128KB	192KB	240KB
PF_LOW	0x3C000	0x38000	0x34000	0x30000	0x28000	0x20000	0x10000	0x04000
PF_LOW_UNP (unpaged) ¹	0xC000	0x8000	0x4000	_	_	_	_	_
PPAGES	0x0F	0x0E - 0x0F	0x0D - 0x0F	0x0C - 0x0F	0x0A - 0x0F	0x08 - 0x0F	0x04 - 0x0F	0x01 - 0x0F
EEPROM [Bytes]	512	1024	1536	2048	3072	4096	4096	4096
EEPROM_HI	0x05FF	0x07FF	0x09FF	0x0BFF	0x0FFF	0x13FF	0x13FF	0x13FF

The SCI2 is not available on the S12GN8, S12GN16, S12GN32, S12GN32, S12GA8, and S12G64 devices

³ The SPI1 is not available on the S12GN8, S12GN16, S12GN24, and S12GN32 devices

⁴ The SPI2 is not available on the S12GN8, S12GN16, S12GN32, S12GN32, S12GA8, and S12G64 devices

The CAN is not available on the S12GN8, S12GN16, S12GN24, S12GN32, and S12GN48 devices

The ACMP is only available on the S12GN8, S12GN16, S12GN24, S12GN32, S12GN48, S12GN48, S12G48, and S12G64 devices

⁷ The RVA is only available on the S12GA192 and S12GA240 devices

⁸ DAC0 and DAC1 are only available on the S12GA192 and S12GA240 devices

Port Integration Module (S12GPIMV1)

Table 2-19. Block Register Map (G1) (continued)

Global Address Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0255 PPSM	R W	0	0	0	0	PPSM3	PPSM2	PPSM1	PPSM0
0x0256 WOMM	R W	0	0	0	0	WOMM3	WOMM2	WOMM1	WOMM0
0x0257 PKGCR	R W	APICLKS7	0	0	0	0	PKGCR2	PKGCR1	PKGCR0
0x0258 PTP	R W	PTP7	PTP6	PTP5	PTP4	PTP3	PTP2	PTP1	PTP0
0x0259 PTIP	R W	PTIP7	PTIP6	PTIP5	PTIP4	PTIP3	PTIP2	PTIP1	PTIP0
0x025A DDRP	R W	DDRP7	DDRP6	DDRP5	DDRP4	DDRP3	DDRP2	DDRP1	DDRP0
0x025B Reserved	R W	0	0	0	0	0	0	0	0
0x025C PERP	R W	PERP7	PERP6	PERP5	PERP4	PERP3	PERP2	PERP1	PERP0
0x025D PPSP	R W	PPSP7	PPSP6	PPSP5	PPSP4	PPSP3	PPSP2	PPSP1	PPSP0
0x025E PIEP	R W	PIEP7	PIEP6	PIEP5	PIEP4	PIEP3	PIEP2	PIEP1	PIEP0
0x025F PIFP	R W	PIFP7	PIFP6	PIFP5	PIFP4	PIFP3	PIFP2	PIFP1	PIFP0
0x0260-0x0267 Reserved	R W	0	0	0	0	0	0	0	0
0x0268 PTJ	R W	PTJ7	PTJ6	PTJ5	PTJ4	PTJ3	PTJ2	PTJ1	PTJ0
0x0269 PTIJ	R W	PTIJ7	PTIJ6	PTIJ5	PTIJ4	PTIJ3	PTIJ2	PTIJ1	PTIJ0
0x026A DDRJ	R W	DDRJ7	DDRJ6	DDRJ5	DDRJ4	DDRJ3	DDRJ2	DDRJ1	DDRJ0
			= Unimplem	nented or Re	served				

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Table 2-42. DDRS Register Field Descriptions

Field	Description
7-0 DDRS	Port S data direction— This bit determines whether the associated pin is a general-purpose input or output.
	Associated pin configured as output Associated pin configured as input

2.4.3.23 Port S Pull Device Enable Register (PERS)

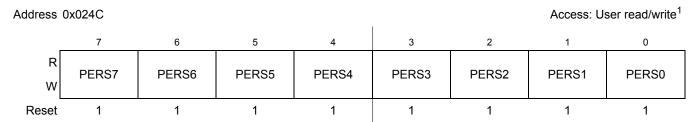


Figure 2-24. Port S Pull Device Enable Register (PERS)

Table 2-43. PERS Register Field Descriptions

Field	Description
7-0 PERS	Port S pull device enable—Enable pull device on input pin or wired-or output pin This bit controls whether a pull device on the associated port input pin is active. The polarity is selected by the related polarity select register bit. If a pin is used as output this bit has only effect if used in wired-or mode with a pullup device.
	1 Pull device enabled 0 Pull device disabled

2.4.3.24 Port S Polarity Select Register (PPSS)

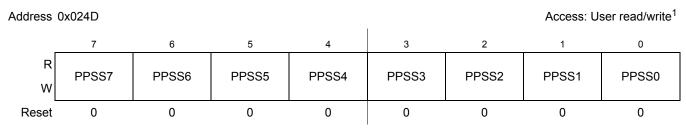


Figure 2-25. Port S Polarity Select Register (PPSS)

Read: Anytime Write: Anytime

Read: Anytime Write: Anytime

Table 2-70. DDRJ Register Field Descriptions

Field	Description			
7-0 DDRJ	Port J data direction— This bit determines whether the associated pin is an input or output. 1 Associated pin configured as output 0 Associated pin configured as input			

2.4.3.45 Port J Pull Device Enable Register (PERJ)

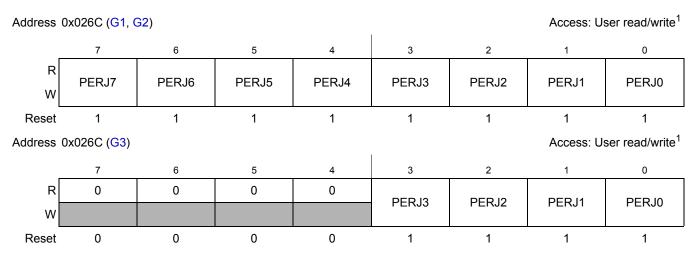


Figure 2-45. Port J Pull Device Enable Register (PERJ)

Table 2-71. PERJ Register Field Descriptions

	Field	Description
•	7-0 PERJ	Port J pull device enable—Enable pull device on input pin This bit controls whether a pull device on the associated port input pin is active. If a pin is used as output this bit has no effect. The polarity is selected by the related polarity select register bit. 1 Pull device enabled 0 Pull device disabled
		U Puli device disabled

Read: Anytime Write: Anytime

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Figure 7-2. BDM Register Summary (continued)

7.3.2.1 BDM Status Register (BDMSTS)

Register Global Address 0x3 FF01



ENBDM is read as 1 by a debugging environment in special single chip mode when the device is not secured or secured but fully erased (Flash). This is because the ENBDM bit is set by the standard BDM firmware before a BDM command can be fully transmitted and executed.

Figure 7-3. BDM Status Register (BDMSTS)

Read: All modes through BDM operation when not secured

Write: All modes through BDM operation when not secured, but subject to the following:

- ENBDM should only be set via a BDM hardware command if the BDM firmware commands are needed. (This does not apply in special single chip mode).
- BDMACT can only be set by BDM hardware upon entry into BDM. It can only be cleared by the standard BDM firmware lookup table upon exit from BDM active mode.
- All other bits, while writable via BDM hardware or standard BDM firmware write commands, should only be altered by the BDM hardware or standard firmware lookup table as part of BDM command execution.

² UNSEC is read as 1 by a debugging environment in special single chip mode when the device is secured and fully erased, else it is 0 and can only be read if not secure (see also bit description).

S12S Debug Module (S12SDBGV2)

Read: Anytime

Write: Bit 6 only when DBG is neither secure nor armed.Bits 3,2,0 anytime the module is disarmed.

Table 8-7. DBGTCR Field Descriptions

Field	Description
6 TSOURCE	Trace Source Control Bit — The TSOURCE bit enables a tracing session given a trigger condition. If the MCU system is secured, this bit cannot be set and tracing is inhibited. This bit must be set to read the trace buffer. Debug session without tracing requested Debug session with tracing requested
3–2 TRCMOD	Trace Mode Bits — See Section 8.4.5.2, "Trace Modes for detailed Trace Mode descriptions. In Normal Mode, change of flow information is stored. In Loop1 Mode, change of flow information is stored but redundant entries into trace memory are inhibited. In Detail Mode, address and data for all memory and register accesses is stored. In Compressed Pure PC mode the program counter value for each instruction executed is stored. See Table 8-8.
0 TALIGN	Trigger Align Bit — This bit controls whether the trigger is aligned to the beginning or end of a tracing session. O Trigger at end of stored data 1 Trigger before storing data

Table 8-8. TRCMOD Trace Mode Bit Encoding

TRCMOD	Description
00	Normal
01	Loop1
10	Detail
11	Compressed Pure PC

8.3.2.4 Debug Control Register2 (DBGC2)

Address: 0x0023



Figure 8-6. Debug Control Register2 (DBGC2)

Read: Anytime

Write: Anytime the module is disarmed.

This register configures the comparators for range matching.

Table 8-9. DBGC2 Field Descriptions

Field	Description
	A and B Comparator Match Control — These bits determine the A and B comparator match mapping as described in Table 8-10.

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NOTE

A write to this register starts the RTI time-out period. A change of the RTIOSCSEL bit (writing a different value or loosing UPOSC status) re-starts the RTI time-out period.

Table 10-9. CPMURTI Field Descriptions

Field	Description
7 RTDEC	Decimal or Binary Divider Select Bit — RTDEC selects decimal or binary based prescaler values. 0 Binary based divider value. See Table 10-10 1 Decimal based divider value. See Table 10-11
6–4 RTR[6:4]	Real Time Interrupt Prescale Rate Select Bits — These bits select the prescale rate for the RTI. See Table 10-10 and Table 10-11.
3–0 RTR[3:0]	Real Time Interrupt Modulus Counter Select Bits — These bits select the modulus counter target value to provide additional granularity. Table 10-10 and Table 10-11 show all possible divide values selectable by the CPMURTI register.

Table 10-10. RTI Frequency Divide Rates for RTDEC = 0

	RTR[6:4] =							
RTR[3:0]	000 (OFF)	001 (2 ¹⁰)	010 (2 ¹¹)	011 (2 ¹²)	100 (2 ¹³)	101 (2 ¹⁴)	110 (2 ¹⁵)	111 (2 ¹⁶)
0000 (÷1)	OFF ¹	2 ¹⁰	2 ¹¹	2 ¹²	2 ¹³	2 ¹⁴	2 ¹⁵	2 ¹⁶
0001 (÷2)	OFF	2x2 ¹⁰	2x2 ¹¹	2x2 ¹²	2x2 ¹³	2x2 ¹⁴	2x2 ¹⁵	2x2 ¹⁶
0010 (÷3)	OFF	3x2 ¹⁰	3x2 ¹¹	3x2 ¹²	3x2 ¹³	3x2 ¹⁴	3x2 ¹⁵	3x2 ¹⁶
0011 (÷4)	OFF	4x2 ¹⁰	4x2 ¹¹	4x2 ¹²	4x2 ¹³	4x2 ¹⁴	4x2 ¹⁵	4x2 ¹⁶
0100 (÷5)	OFF	5x2 ¹⁰	5x2 ¹¹	5x2 ¹²	5x2 ¹³	5x2 ¹⁴	5x2 ¹⁵	5x2 ¹⁶
0101 (÷6)	OFF	6x2 ¹⁰	6x2 ¹¹	6x2 ¹²	6x2 ¹³	6x2 ¹⁴	6x2 ¹⁵	6x2 ¹⁶
0110 (÷7)	OFF	7x2 ¹⁰	7x2 ¹¹	7x2 ¹²	7x2 ¹³	7x2 ¹⁴	7x2 ¹⁵	7x2 ¹⁶
0111 (÷8)	OFF	8x2 ¹⁰	8x2 ¹¹	8x2 ¹²	8x2 ¹³	8x2 ¹⁴	8x2 ¹⁵	8x2 ¹⁶
1000 (÷9)	OFF	9x2 ¹⁰	9x2 ¹¹	9x2 ¹²	9x2 ¹³	9x2 ¹⁴	9x2 ¹⁵	9x2 ¹⁶
1001 (÷10)	OFF	10x2 ¹⁰	10x2 ¹¹	10x2 ¹²	10x2 ¹³	10x2 ¹⁴	10x2 ¹⁵	10x2 ¹⁶
1010 (÷11)	OFF	11x2 ¹⁰	11x2 ¹¹	11x2 ¹²	11x2 ¹³	11x2 ¹⁴	11x2 ¹⁵	11x2 ¹⁶
1011 (÷12)	OFF	12x2 ¹⁰	12x2 ¹¹	12x2 ¹²	12x2 ¹³	12x2 ¹⁴	12x2 ¹⁵	12x2 ¹⁶
1100 (÷13)	OFF	13x2 ¹⁰	13x2 ¹¹	13x2 ¹²	13x2 ¹³	13x2 ¹⁴	13x2 ¹⁵	13x2 ¹⁶
1101 (÷14)	OFF	14x2 ¹⁰	14x2 ¹¹	14x2 ¹²	14x2 ¹³	14x2 ¹⁴	14x2 ¹⁵	14x2 ¹⁶

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11.3.2.10 ATD Input Enable Register (ATDDIEN)

Module Base + 0x000C

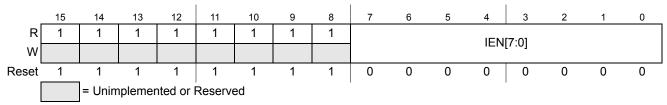


Figure 11-12. ATD Input Enable Register (ATDDIEN)

Read: Anytime Write: Anytime

Table 11-19. ATDDIEN Field Descriptions

Field	Description
7–0 IEN[7:0]	 ATD Digital Input Enable on channel x (x= 7, 6, 5, 4, 3, 2, 1, 0) — This bit controls the digital input buffer from the analog input pin (ANx) to the digital data register. Disable digital input buffer to ANx pin Enable digital input buffer on ANx pin. Note: Setting this bit will enable the corresponding digital input buffer continuously. If this bit is set while simultaneously using it as an analog port, there is potentially increased power consumption because the digital input buffer maybe in the linear region.

11.3.2.11 ATD Compare Higher Than Register (ATDCMPHT)

Writes to this register will abort current conversion sequence.

Read: Anytime Write: Anytime

Module Base + 0x000E

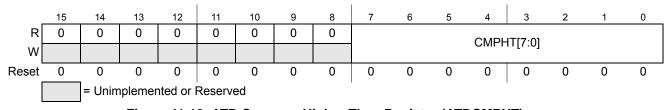


Figure 11-13. ATD Compare Higher Than Register (ATDCMPHT)

Table 11-20. ATDCMPHT Field Descriptions

Field	Description
	Compare Operation Higher Than Enable for conversion number <i>n</i> (<i>n</i> = 7, 6, 5, 4, 3, 2, 1, 0) of a Sequence (<i>n conversion number, NOT channel number!</i>) — This bit selects the operator for comparison of conversion results.
	0 If result of conversion <i>n</i> is lower or same than compare value in ATDDR <i>n</i> , this is flagged in ATDSTAT2 1 If result of conversion <i>n</i> is higher than compare value in ATDDR <i>n</i> , this is flagged in ATDSTAT2

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18.4.3.1 Protocol Violation Protection

The MSCAN protects the user from accidentally violating the CAN protocol through programming errors. The protection logic implements the following features:

- The receive and transmit error counters cannot be written or otherwise manipulated.
- All registers which control the configuration of the MSCAN cannot be modified while the MSCAN is on-line. The MSCAN has to be in Initialization Mode. The corresponding INITRQ/INITAK handshake bits in the CANCTL0/CANCTL1 registers (see Section 18.3.2.1, "MSCAN Control Register 0 (CANCTL0)") serve as a lock to protect the following registers:
 - MSCAN control 1 register (CANCTL1)
 - MSCAN bus timing registers 0 and 1 (CANBTR0, CANBTR1)
 - MSCAN identifier acceptance control register (CANIDAC)
 - MSCAN identifier acceptance registers (CANIDAR0–CANIDAR7)
 - MSCAN identifier mask registers (CANIDMR0–CANIDMR7)
- The TXCAN is immediately forced to a recessive state when the MSCAN goes into the power down mode or initialization mode (see Section 18.4.5.6, "MSCAN Power Down Mode," and Section 18.4.4.5, "MSCAN Initialization Mode").
- The MSCAN enable bit (CANE) is writable only once in normal system operation modes, which provides further protection against inadvertently disabling the MSCAN.

18.4.3.2 Clock System

Figure 18-43 shows the structure of the MSCAN clock generation circuitry.

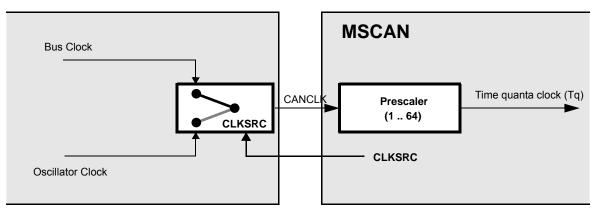


Figure 18-43. MSCAN Clocking Scheme

The clock source bit (CLKSRC) in the CANCTL1 register (18.3.2.2/18-576) defines whether the internal CANCLK is connected to the output of a crystal oscillator (oscillator clock) or to the bus clock.

The clock source has to be chosen such that the tight oscillator tolerance requirements (up to 0.4%) of the CAN protocol are met. Additionally, for high CAN bus rates (1 Mbps), a 45% to 55% duty cycle of the clock is required.

If the bus clock is generated from a PLL, it is recommended to select the oscillator clock rather than the bus clock due to jitter considerations, especially at the faster CAN bus rates.

21.3.2.3 SPI Baud Rate Register (SPIBR)

Module Base +0x0002

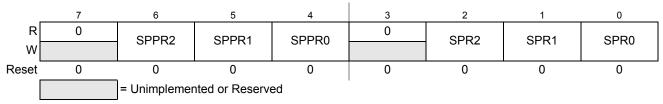


Figure 21-5. SPI Baud Rate Register (SPIBR)

Read: Anytime

Write: Anytime; writes to the reserved bits have no effect

Table 21-5. SPIBR Field Descriptions

Field	Description
6–4 SPPR[2:0]	SPI Baud Rate Preselection Bits — These bits specify the SPI baud rates as shown in Table 21-6. In master mode, a change of these bits will abort a transmission in progress and force the SPI system into idle state.
	SPI Baud Rate Selection Bits — These bits specify the SPI baud rates as shown in Table 21-6. In master mode, a change of these bits will abort a transmission in progress and force the SPI system into idle state.

The baud rate divisor equation is as follows:

Eqn. 21-1

The baud rate can be calculated with the following equation:

Baud Rate = BusClock / BaudRateDivisor

Eqn. 21-2

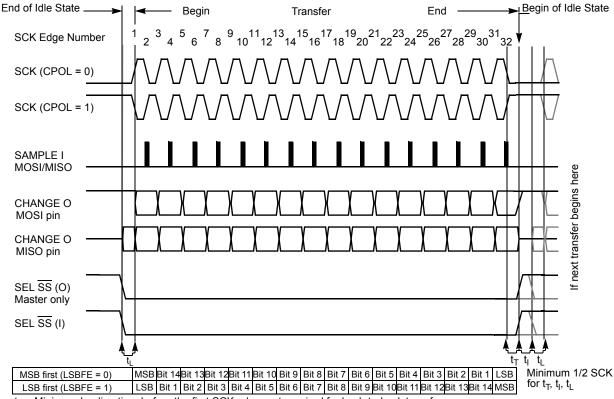
NOTE

For maximum allowed baud rates, please refer to the SPI Electrical Specification in the Electricals chapter of this data sheet.

Table 21-6. Example SPI Baud Rate Selection (25 MHz Bus Clock)

SPPR2	SPPR1	SPPR0	SPR2	SPR1	SPR0	Baud Rate Divisor	Baud Rate
0	0	0	0	0	0	2	12.5 Mbit/s
0	0	0	0	0	1	4	6.25 Mbit/s
0	0	0	0	1	0	8	3.125 Mbit/s
0	0	0	0	1	1	16	1.5625 Mbit/s
0	0	0	1	0	0	32	781.25 kbit/s
0	0	0	1	0	1	64	390.63 kbit/s
0	0	0	1	1	0	128	195.31 kbit/s
0	0	0	1	1	1	256	97.66 kbit/s
0	0	1	0	0	0	4	6.25 Mbit/s
0	0	1	0	0	1	8	3.125 Mbit/s

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 t_L = Minimum leading time before the first SCK edge, not required for back-to-back transfers

Figure 21-15. SPI Clock Format 1 (CPHA = 1), with 16-Bit Transfer Width selected (XFRW = 1)

The SS line can remain active low between successive transfers (can be tied low at all times). This format is sometimes preferred in systems having a single fixed master and a single slave that drive the MISO data line.

• Back-to-back transfers in master mode
In master mode, if a transmission has completed and new data is available in the SPI data register, this data is sent out immediately without a trailing and minimum idle time.

The SPI interrupt request flag (SPIF) is common to both the master and slave modes. SPIF gets set one half SCK cycle after the last SCK edge.

21.4.4 SPI Baud Rate Generation

Baud rate generation consists of a series of divider stages. Six bits in the SPI baud rate register (SPPR2, SPPR1, SPPR0, SPR2, SPR1, and SPR0) determine the divisor to the SPI module clock which results in the SPI baud rate.

The SPI clock rate is determined by the product of the value in the baud rate preselection bits (SPPR2–SPPR0) and the value in the baud rate selection bits (SPR2–SPR0). The module clock divisor equation is shown in Equation 21-3.

t_T = Minimum trailing time after the last SCK edge

t₁ = Minimum idling time between transfers (minimum \overline{SS} high time), not required for back-to-back transfers

Timer Module (TIM16B8CV3)

Write: Anytime.

Table 23-11. TCTL3/TCTL4 Field Descriptions

Note: Writing to unavailable bits has no effect. Reading from unavailable bits return a zero.

Field	Description
7:0 EDGnB EDGnA	Input Capture Edge Control — These eight pairs of control bits configure the input capture edge detector circuits.

Table 23-12. Edge Detector Circuit Configuration

EDGnB	EDGnA	Configuration
0	0	Capture disabled
0	1	Capture on rising edges only
1	0	Capture on falling edges only
1	1	Capture on any edge (rising or falling)

23.3.2.10 Timer Interrupt Enable Register (TIE)

Module Base + 0x000C

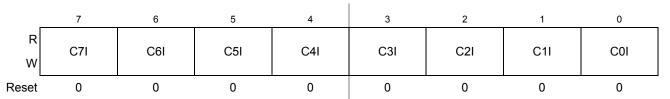


Figure 23-18. Timer Interrupt Enable Register (TIE)

Read: Anytime Write: Anytime.

Table 23-13. TIE Field Descriptions

Note: Writing to unavailable bits has no effect. Reading from unavailable bits return a zero

Field	Description
C7I:C0I	Input Capture/Output Compare "x" Interrupt Enable — The bits in TIE correspond bit-for-bit with the bits in the TFLG1 status register. If cleared, the corresponding flag is disabled from causing a hardware interrupt. If set, the corresponding flag is enabled to cause a interrupt.

24.4.7 Interrupts

The Flash module can generate an interrupt when a Flash command operation has completed or when a Flash command operation has detected an ECC fault.

Interrupt Source	Interrupt Flag	Local Enable	Global (CCR) Mask
Flash Command Complete	CCIF (FSTAT register)	CCIE (FCNFG register)	l Bit
ECC Double Bit Fault on Flash Read	DFDIF (FERSTAT register)	DFDIE (FERCNFG register)	I Bit
ECC Single Bit Fault on Flash Read	SFDIF (FERSTAT register)	SFDIE (FERCNFG register)	I Bit

Table 24-64. Flash Interrupt Sources

NOTE

Vector addresses and their relative interrupt priority are determined at the MCU level.

24.4.7.1 Description of Flash Interrupt Operation

The Flash module uses the CCIF flag in combination with the CCIE interrupt enable bit to generate the Flash command interrupt request. The Flash module uses the DFDIF and SFDIF flags in combination with the DFDIE and SFDIE interrupt enable bits to generate the Flash error interrupt request. For a detailed description of the register bits involved, refer to Section 24.3.2.5, "Flash Configuration Register (FCNFG)", Section 24.3.2.6, "Flash Error Configuration Register (FERCNFG)", Section 24.3.2.7, "Flash Status Register (FSTAT)", and Section 24.3.2.8, "Flash Error Status Register (FERSTAT)".

The logic used for generating the Flash module interrupts is shown in Figure 24-26.

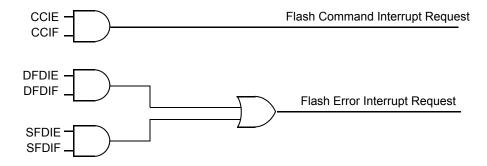


Figure 24-26. Flash Module Interrupts Implementation

Offset Module Base + 0x000E

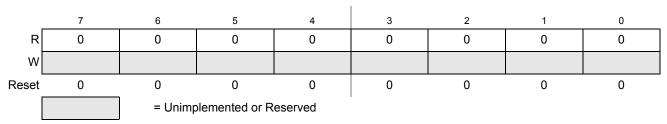


Figure 25-20. Flash Reserved3 Register (FRSV3)

All bits in the FRSV3 register read 0 and are not writable.

25.3.2.15 Flash Reserved4 Register (FRSV4)

This Flash register is reserved for factory testing.

Offset Module Base + 0x000F

Offset Module Base + 0x0010

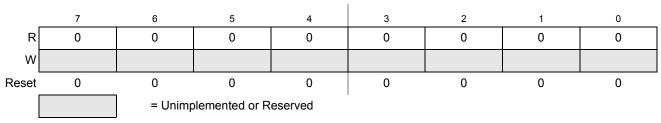


Figure 25-21. Flash Reserved4 Register (FRSV4)

All bits in the FRSV4 register read 0 and are not writable.

25.3.2.16 Flash Option Register (FOPT)

The FOPT register is the Flash option register.

Figure 25-22. Flash Option Register (FOPT)

All bits in the FOPT register are readable but are not writable.

During the reset sequence, the FOPT register is loaded from the Flash nonvolatile byte in the Flash configuration field at global address 0x3_FF0E located in P-Flash memory (see Table 25-4) as indicated by reset condition F in Figure 25-22. If a double bit fault is detected while reading the P-Flash phrase containing the Flash nonvolatile byte during the reset sequence, all bits in the FOPT register will be set.

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¹ Loaded from IFR Flash configuration field, during reset sequence.

Table 25-61. Erase Verify EEPROM Section Command Error Handling

Register	Error Bit	Error Condition
		Set if CCOBIX[2:0] != 010 at command launch
		Set if command not available in current mode (see Table 25-27)
	ACCERR STAT FPVIOL	Set if an invalid global address [17:0] is supplied
		Set if a misaligned word address is supplied (global address [0] != 0)
FSTAT		Set if the requested section breaches the end of the EEPROM block
		None
	MGSTAT1	Set if any errors have been encountered during the read or if blank check failed.
	MGSTAT0	Set if any non-correctable errors have been encountered during the read or if blank check failed.

25.4.6.15 Program EEPROM Command

The Program EEPROM operation programs one to four previously erased words in the EEPROM block. The Program EEPROM operation will confirm that the targeted location(s) were successfully programmed upon completion.

CAUTION

A Flash word must be in the erased state before being programmed. Cumulative programming of bits within a Flash word is not allowed.

Table 25-62. Program EEPROM Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters					
000	0x11	Global address [17:16] to identify the EEPROM block				
001	Global address [15:0] of word to be programmed					
010	Word 0 program value					
011	Word 1 program value, if desired					
100	Word 2 program value, if desired					
101	Word 3 program value, if desired					

Upon clearing CCIF to launch the Program EEPROM command, the user-supplied words will be transferred to the Memory Controller and be programmed if the area is unprotected. The CCOBIX index value at Program EEPROM command launch determines how many words will be programmed in the EEPROM block. The CCIF flag is set when the operation has completed.

Offset Module Base + 0x0000

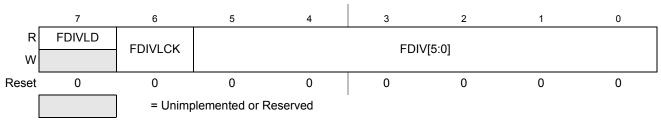


Figure 30-5. Flash Clock Divider Register (FCLKDIV)

All bits in the FCLKDIV register are readable, bit 7 is not writable, bit 6 is write-once-hi and controls the writability of the FDIV field in normal mode. In special mode, bits 6-0 are writable any number of times but bit 7 remains unwritable.

CAUTION

The FCLKDIV register should never be written while a Flash command is executing (CCIF=0).

Table 30-7. FCLKDIV Field Descriptions

Field	Description
7 FDIVLD	Clock Divider Loaded 0 FCLKDIV register has not been written since the last reset 1 FCLKDIV register has been written since the last reset
6 FDIVLCK	Clock Divider Locked 0 FDIV field is open for writing 1 FDIV value is locked and cannot be changed. Once the lock bit is set high, only reset can clear this bit and restore writability to the FDIV field in normal mode.
5–0 FDIV[5:0]	Clock Divider Bits — FDIV[5:0] must be set to effectively divide BUSCLK down to 1 MHz to control timed events during Flash program and erase algorithms. Table 30-8 shows recommended values for FDIV[5:0] based on the BUSCLK frequency. Please refer to Section 30.4.4, "Flash Command Operations," for more information.

30.4.6 Flash Command Description

This section provides details of all available Flash commands launched by a command write sequence. The ACCERR bit in the FSTAT register will be set during the command write sequence if any of the following illegal steps are performed, causing the command not to be processed by the Memory Controller:

- Starting any command write sequence that programs or erases Flash memory before initializing the FCLKDIV register
- Writing an invalid command as part of the command write sequence
- For additional possible errors, refer to the error handling table provided for each command

If a Flash block is read during execution of an algorithm (CCIF = 0) on that same block, the read operation will return invalid data if both flags SFDIF and DFDIF are set. If the SFDIF or DFDIF flags were not previously set when the invalid read operation occurred, both the SFDIF and DFDIF flags will be set.

If the ACCERR or FPVIOL bits are set in the FSTAT register, the user must clear these bits before starting any command write sequence (see Section 30.3.2.7).

CAUTION

A Flash word or phrase must be in the erased state before being programmed. Cumulative programming of bits within a Flash word or phrase is not allowed.

30.4.6.1 Erase Verify All Blocks Command

The Erase Verify All Blocks command will verify that all P-Flash and EEPROM blocks have been erased.

Table 30-31. Erase Verify All Blocks Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters				
000	0x01	Not required			

Upon clearing CCIF to launch the Erase Verify All Blocks command, the Memory Controller will verify that the entire Flash memory space is erased. The CCIF flag will set after the Erase Verify All Blocks operation has completed. If all blocks are not erased, it means blank check failed, both MGSTAT bits will be set.

Table 30-32. Erase Verify All Blocks Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 000 at command launch
	FPVIOL	None
	MGSTAT1	Set if any errors have been encountered during the reador if blank check failed .
	MGSTAT0	Set if any non-correctable errors have been encountered during the read or if blank check failed.

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Table A-31. ACMP Electrical Characteristics (Junction Temperature From -40°C To +150°C)

Characteristics noted under conditions 3.13V <= VDDA <= 5.5V, $-40^{\circ}C$ < Tj < $150^{\circ}C$ unless otherwise noted. Typical values noted reflect the approximate parameter mean at T_A = $25^{\circ}C$ under nominal conditions unless otherwise noted.

Num	С	Ratings	Symbol	Min	Тур	Max	Unit
1	D C	Supply Current of ACMP module disabled module enabled $\Delta V_{in} > 0.1V$	I _{off} I _{run}	100	- 180	5 270	μ Α μ Α
2	Р	Common mode Input voltage range ACMPM, ACMPP	V _{in}	0	-	V _{DDA} -1.5V	V
3	Р	Input Offset	V _{offset}	-40	0	40	mV
4	С	Input Hysteresis	V _{hyst}	3	7	20	mV
5	Р	Switch delay for -0.1V to 0.1V input step (w/o synchronize delay)	t _{delay}	-	0.3	0.6	μ\$

Table A-32. ACMP Electrical Characteristics (Junction Temperature From +150°C To +160°C)

Characteristics noted under conditions 3.13V <= VDDA <= 5.5V, $-150^{\circ}C$ < Tj < $160^{\circ}C$ unless otherwise noted. Typical values noted reflect the approximate parameter mean at T_A = $25^{\circ}C$ under nominal conditions unless otherwise noted.

Num	С	Ratings	Symbol	Min	Тур	Max	Unit
1	D C	Supply Current of ACMP module disabled module enabled $\Delta V_{in} > 0.1V$	I _{off} I _{run}		- 180		μ Α μ Α
2	М	Common mode Input voltage range ACMPM, ACMPP	V _{in}		-		V
3	М	Input Offset	V _{offset}		0		mV
4	С	Input Hysteresis	V _{hyst}		7		mV
5	М	Switch delay for -0.1V to 0.1V input step (w/o synchronize delay)	t _{delay}		0.3		μ\$